



## IEEE EPS Vietnam Chapter

On **June 20th** of this year, the **IEEE EPS Vietnam chapter** was established, marking a significant accomplishment that was the result of a long-standing vision. The EPS Malaysia chapter provided generous support and **Dr. ANDREW TAY** for this achievement. The core team of the IEEE EPS Vietnam chapter includes tech leaders from **Intel** and **Onsemi**, with **Mike Fadreguilan** from Intel Products Vietnam Co., Ltd. (1st person from left) serving as the first chapter chair.



## IEEE EPS Vietnam Chapter Executive Team



On 25<sup>th</sup> of August, 2023, the EPS Malaysia chapter's executive team delivered a talk on how to run a successful EPS chapter during their trip to Vietnam. The EPS Vietnam chapter team was fully engaged and gained invaluable insights from the presentations.



# IEEE EPS Vietnam Chapter Tech Day

In an impressive display of engagement, less than two months after the chapter's inception, **the first IEEE EPS Vietnam chapter Tech Day** event was held in successful collaboration with the **EPS Malaysia** chapter executive team 25<sup>th</sup> of August 2023. The event saw participation from **11 Onsemi staff and engineers**, and **3 academia professors on-site**, while more than **200 Intel employees** joined in, and with the presence of **Kenneth Tse Intel Vice President** making this an unforgettable and historic occasion.



Three distinguished speakers from the **EPS Malaysia** chapter shared their knowledge on advanced packaging. **Dr. Tan Yik Yee**, from Yole Intelligence, talked about the latest market and technology trends. **Dr. Siow Kim Shyong**, from the National University of Malaysia, provided valuable insights on scientific writing for publication. **Dr. Eu Poh Leng**, from NXP, discussed the role of advanced semiconductor packaging in creating a smarter world.

The event also featured a Q&A session, where audience members got the chance to ask questions and win gifts from the speakers.

Especially, **Dr. Eu Poh Leng**, the current chairman of EPS Malaysia committee, recently shared her **expert insights on how to succeed in Semiconductor Packaging**. Her four key takeaways are vital: 1) *Believe in yourself, and you can achieve anything*, 2) *Put your heart into everything you do, and success will follow*, 3) *Demonstrate integrity to be seen as trustworthy and dependable*, and 4) *Stay away from making enemies*.



With the exciting developments happening in the semiconductor industry, particularly in Packaging, we would like to extend our gratitude to IEEE EPS Vietnam and Malaysia chapters and Onsemi. **A Special Thanks to Intel Products Vietnam for hosting the event.**



Let's look back at the key moments of EPS Tech Day Events

